

Preliminary Product Information Sheet

EPO-TEK® OG147-51 (formerly 90-76-2)

Note: These are typical properties to be used as a guide only, not a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.

| Date: | September 2017 | Recommended Cure: 120°C / 1 Hour |
|----------------------|-----------------------|---|
| Rev: | V | |
| No. of Components: | Single | Minimum Alternative Cure(s): |
| Mix Ratio by Weight: | N/A | May not achieve performance properties listed below |
| Specific Gravity: | 1.30 | 150°C / 5 Minutes |
| Pot Life: | 28 Days | 125°C / 20 Minutes |
| Shelf Life- Bulk: | One year refrigerated | |

NOTES:

• Container(s) should be kept closed when not in use.

• Filled systems should be stirred thoroughly before mixing and prior to use.

• Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A single component, semi-flexible epoxy adhesive designed for low stress bonding of fiber optic component applications. It is a thixotropic adhesive which can be applied by dispensing or screen printing techniques. It has a very long pot-life, capable of fast curing techniques.

MATERIAL CHARACTERISTICS*:

| PHYSICAL PROPERTIES: | | Cure condition | : 120°C / 1 Hour | |
|----------------------------------|------------------|----------------|--|--|
| Color (before cure): | | Black | | |
| Consistency: | | Smooth paste | | |
| Viscosity (23°C) @ 100 rpm: | | 1,864 | cPs | |
| Thixotropic Index: | | 2.7 | | |
| Glass Transition Temp: | | 33 | °C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min) | |
| Coefficient of Thermal Expans | ion (CTE): | | | |
| | Below Tg: | 57 | x 10 ⁻⁶ in/in°C | |
| | Above Tg: | 178 | x 10 ⁻⁶ in/in°C | |
| Shore D Hardness: | C C | 84 | | |
| Lap Shear @ 23°C: | | | psi | |
| Die Shear @ 23°C: | | 17 | Kg | |
| Degradation Temp: | | 376 | °Č | |
| Weight Loss: | | | | |
| | @ 200°C: | < 0.05 | % | |
| | @ 250°C: | 0.15 | % | |
| | @ 300°C: | 0.75 | % | |
| Suggested Operating Temperature: | | < 300 | °C (Intermittent) | |
| Storage Modulus: | | 142,857 | psi | |
| Particle Size: | | ≤ 20 | microns | |
| OPTICAL PROPERTIES @ 23°C: | | | | |
| Spectral Transmission: | < 20% @ 300-1600 | | nm | |
| Refractive Index: | | N/A | | |

The data above is INITIAL only - it may be changed at any time, for any reason without notice to anyone. It is provided only as a guide for evaluation/consideration.

* These material characteristics are typical properties that are based on a limited number of samples/batches. All properties are based on the cure indicated above. Some properties may vary as manufactured quantities are scaled up to commercialized production levels.

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